

AMENDMENTS TO THE SPECIFICATION:

Please replace the Abstract with the following amended Abstract:

ABSTRACT OF THE DISCLOSURE

An integrated circuit device has an integrated circuit $[(2)]$ formed on a front surface of a silicon substrate $[(1)]$, an insulating layer $[(12)]$ formed on a rear surface of the substrate $[(1)]$, and connection piles $[(4)]$ penetrating the substrate $[(1)]$, the integrated circuit $[(2)]$, and the insulating layer $[(12)]$. An electronic device has plural integrated circuit devices $[(5a,5b)]$ laminated in a multilayer structure, in which a connection pile $[(4a)]$ formed in an integrated circuit $[(2a)]$ in the device $[(5a)]$ as an upper position in the multilayer structure is electrically connected to a connection pile $[(4b)]$ formed in an integrated circuit $[(2b)]$ as a lower position under a requirement of an electric connection for the piles $[(4a,4b)]$. The pile $[(4a)]$ is electrically insulated from the pile $[(4b)]$ through the insulating layer $[(12)]$ under no requirement of the electric connection for them.